

7. (Amended) The method of fabricating a semiconductor device as defined in claim 5, further comprising:

cutting the substrate into the semiconductor chips after the step (c).

8. (Amended) The method of fabricating a semiconductor device as defined in claim 6, further comprising:

cutting the substrate into the semiconductor chips after the step (c).

B² 9. (Amended) The method of fabricating a semiconductor device as defined in claim 1,

wherein a plurality of device holes are formed in the tape, and leads are formed on the tape, which end portions project into the respective device holes; and

wherein each of the semiconductor chips is disposed within a respective one of the device holes, and the electrodes of the semiconductor chips and the leads are bonded in the step (a).

B³ 11. (Amended) The method of fabricating a semiconductor device as defined in claim 10,

wherein by means of an anisotropic conductive material, the electrodes of the semiconductor chips are lead formed on the tape are electrically connected in the step (a).

13. (Amended) The method of fabricating a semiconductor device as defined in claim 12,

wherein the electrodes of the semiconductor chips and leads formed on the tape are electrically connected by means of wires in the step (a).

B⁴ 14. (Amended) The method of fabricating a semiconductor device as defined in claim 1, further comprising:

attaching a heat radiating member to each of the semiconductor chips.

15. (Amended) The method of fabricating a semiconductor device as defined in claim 2, further comprising:

attaching a heat radiating member to each of the semiconductor chips.

16. (Amended) The method of fabricating a semiconductor device as defined in claim 1, further comprising:

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attaching the heat radiating member before the step (b), with a reel-to-reel transport system.

17. (Amended) The method of fabricating a semiconductor device as defined in claim 2, further comprising:

attaching the heat radiating member before the step (b), with a reel-to-reel transport system.

REMARKS

Claims 1-20 are pending. By this Amendment, claims 1, 2, 7-9, 11 and 13-17 are amended.

Reconsideration based on the following remarks is respectfully requested.

The attached Appendix includes marked-up copies of each rewritten claim (37 C.F.R. §1.121(c)(1)(ii)).

I. The Claims Define Patentable Subject Matter

The Office Action rejects claims 1-20 over claims 1-8 of U.S. Patent No. 6,057,174 based on obviousness-type double patenting. The attached Terminal Disclaimer overcomes this rejection. Withdrawal of the rejection based on obviousness-type double patenting is respectfully requested.

The Office Action also rejects claims 1-20 under 35 U.S.C. §102(e) over Hur (U.S. Patent No. 6,033,933). This rejection is respectfully traversed.